

AMPLE Electronic Technology Co., LTD

2026 /Q4

Disclaimer

- The presentation and discussion contain certain forward-looking statements with respect to the results of operation, financial condition and current expectation.
- The forward-looking statements are subject to known and unknown uncertainties and risks that could cause actual results to differ materially from those expressed or implied by such statements. Such risks and uncertainties include but are not limited to the impact of competitive products and pricing, timely project acceptance by our customers, timely introduction of new technologies, ability to ramp new needs into products, financial stability in end markets, and other risks that AMPLE can not control.
- The forward-looking statements in this release reflect the current belief of AMPLE as of the date of this release and AMPLE undertakes no obligation to update these forward-looking statements for events or circumstances that occur subsequent to such date.

Introduction



- Capital: ~ NTD $ 328 Million
- **Fundraising activities: 2026/05/22**

  Issuance of 4E CB

  Conversion price: 297.6

  Expected share capital expansion: 4%
- **Main Products**：
  - **Advanced packaging heat dissipation and bonding materials**
  - **Flexible circuit board via filling conductive materials**
  - **Passive component conductive materials**
- Location：

  No.32, Dayou 3rd St., Daliao Dist,

  Kaohsiung City, Taiwan

Year 2025《CommonWealth Magazine》Top 50 in 2,000 Operational Performance

2025年《天下》兩千大營運績效50強

天下雜誌 CommonWealth Magazine

排名	公司名稱	'22年～'24年營收成長率(%)	得分	'22年～'24年稅後純益成長率(%)	得分	2024年股東權益報酬率(%)	得分	2024年營收成長率(%)	得分	2024年稅後純益成長率(%)	得分	'22年～'24年稅後純益總和(億元)	得分	總分	主要產品
1	濟南大自然新材料	91.85	20	158.27	19	50.84	20	42.51	19	61.09	16	147.64	19	113	香菸濾嘴用醋酸纖維絲束
2	華城電機	61.45	19	126.15	19	48.85	20	45.35	19	66.32	17	77.01	18	112	配電及電力變壓器等設備
3	名軒開發	109.63	20	101.97	18	30.75	19	68.14	19	52.47	16	49.94	17	109	住宅或商業大樓興建、租售
4	世芯電子	94.59	20	87.48	18	16.33	11	70.49	19	93.86	19	116.05	19	106	特殊應用積體電路設計製造
4	富宇地產	336.52	20	702.84	20	27.95	18	84.33	20	168.56	20	9.84	8	106	住宅或商業大樓興建、租售
6	台光電子材料	29.02	18	37.41	13	27.29	18	55.89	19	74.53	18	201.39	19	105	銅箔基板、黏合片等
6	新潤興業	91.29	20	72.32	17	25.10	17	149.25	20	117.71	19	17.44	12	105	住宅及大樓興建、租售
8	昇益開發	145.76	20	152.32	19	33.16	19	124.26	20	130.12	19	6.08	6	103	住宅及大樓興建、租售
8	皇普建設	75.59	20	133.62	19	18.29	12	188.16	20	436.78	20	17.79	12	103	住宅或商業大樓興建、租售
40	潤德室內裝修設計工程	37.34	18	47.47	15	25.28	17	31.73	17	51.35	15	4.75	4	86	設計與裝修工程
43	中台資源科技	43.14	19	50.74	15	14.95	9	34.98	18	60.39	16	8.44	8	85	廢棄物資源化處理
43	勤凱科技	26.80	17	43.71	14	20.54	14	42.78	19	62.39	17	3.99	4	85	被動元件導電漿
45	力麗科技	52.30	19	29.38	11	22.34	15	99.78	20	35.88	14	5.39	5	84	IoT應用平台暨解決方案
46	肯微科技	24.02	16	36.52	13	9.89	5	32.04	18	78.57	18	21.49	13	83	伺服器電源供應器
46	信鼎技術服務	12.82	11	26.79	10	43.13	20	17.52	14	52.95	16	16.50	12	83	廢棄物資源化處理

2025年營運績效50強調查方法：將過去3年（2022～2024）每年營收、獲利皆持續成長的製造業與服務業，依長期成長、單年表現及企業規模等6項指標評估企業的營運績效。符合上述條件的企業，分別在每項指標中，依數值高低分成20等份，再依據相對位置給予1到20分。最後，將6項指標的得分加總，以總分排名。名次相同者，依公司名稱筆劃排序。

Industry Description

Item	Raw materials/equipment			Remark
CCL	Copper Foil	Glass fiber cloth	Resin	M7/M8/M9/M10
Semiconductor packaging	Wafers	Leadframes	?	Focusing solely on the three major lead frame manufacturers
TGV	glass substrates	laser drilling and conductive via-fill	?	Hole-filling material?
MLCC	?	?	?	Murata/Taiwan Differences >> Materials

- Conductive pastes are critical direct materials, yet they remain heavily reliant on imports and feature extremely high barriers to entry
- Only technical personnel in the industry understand its true importance; as a critical factor influencing quality, it is not something to be altered lightly.
- The absence of comparable companies in the capital market underscores the firm's scarcity and uniqueness.
- There is a lack of research reports on this industry domestically, and the capital market is extremely unfamiliar with it.

MLCC Manufacturing Process

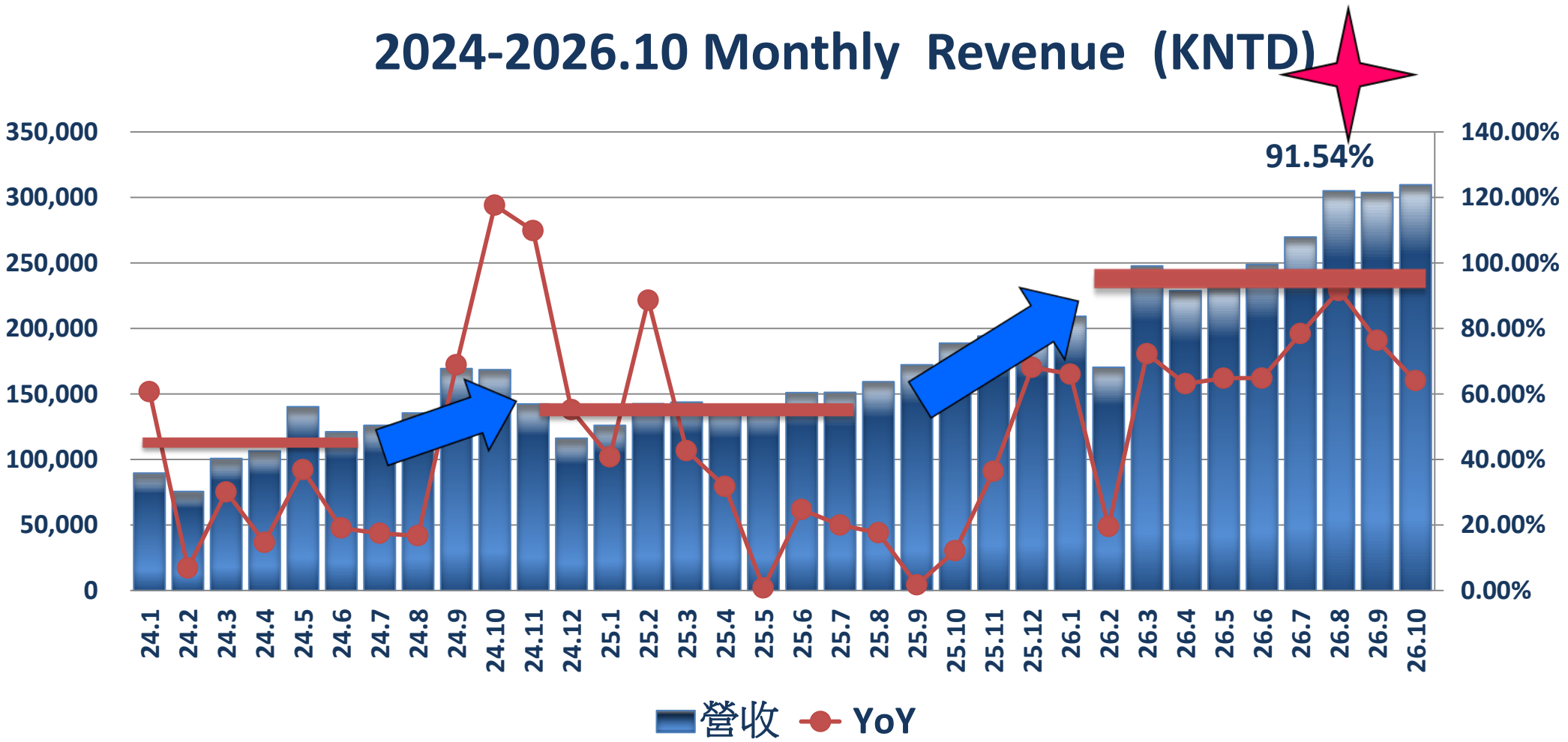


- Conductive paste is used for internal electrode printing and external terminations.
- Material consistency and process compatibility are crucial for performance.
- Applications span high-capacitance and medium-/low-capacitance MLCCs.



- Conductive paste technology has historically been dominated by suppliers from Japan and the United States.
- Key applications include semiconductor packaging, advanced PCBs, MLCCs and thermal management.

Monthly Revenue



Statements of Comprehensive- 2026 Q1/Q2/Q3 Record High

NT$ 千元	2022	2023	2024	2025	2026. Q1	2026. Q2	2026. Q3
營業收人	928, 090	1, 045, 002	1, 491, 879	1, 906, 400	627, 462	710, 778	878, 644
營業毛利	194, 267	224, 069	326, 055	410, 118	123, 851	129, 588	180, 910
毛利率(%)	21%	21%	22%	22%	20%	18%	21%
營業費用	(89, 559)	(95, 247)	(104, 018)	(121, 941)	(34, 682)	(32, 738)	(38, 785)
營業費用率(%)	9%	9%	9%	6%	6%	4%	5%
營業淨利	104, 708	128, 822	222, 037	288, 177	89, 169	96, 850	142, 125
營業淨利率(%)	12%	12%	15%	16%	14%	14%	16%
營業外收支淨額	11, 709	14, 345	15, 758	(9, 720)	9, 965	9, 589	(3, 177)
稅前淨利	116, 417	143, 167	237, 795	278, 457	99, 134	106, 439	138, 948
所得稅費用	(24, 059)	(26, 443)	(48, 028)	(55, 530)	(18, 448)	(20, 784)	(27, 896)
本期淨利	92, 358	116, 724	189, 767	222, 927	80, 686	85, 655	111, 052
淨利率(%)	10%	11%	13%	12%	13%	12%	13%
每股盈餘(元)	3. 08	3. 9	6. 3	7. 05	2. 55	2. 71	3. 44
折舊費用	24, 873	23, 682	23, 271	22, 590	5, 258	5, 161	5, 170
資本支出	12, 419	13, 020	12, 489	9, 427	937	103, 938	4, 511

Dividend Policy

年度	2020	2021	2022	2023	2024	2025
EPS	4.74	6.7	3.08	3.9	6.3	7.05
Cash Dividend	3.2	4.5	2.2	2.7	3.7	4.5
Stock Dividend	–	–	–	–	0.5	0.2
Total Distributed Dividend	3.2	4.5	2.2	2.7	4.2	4.7
Interest Rate	67.51%	67.16%	71.43%	69.23%	66.67%	66.67%

Distributed dividends for 13 consecutive years!

Total dividends distributed: NTD$ 31.4875

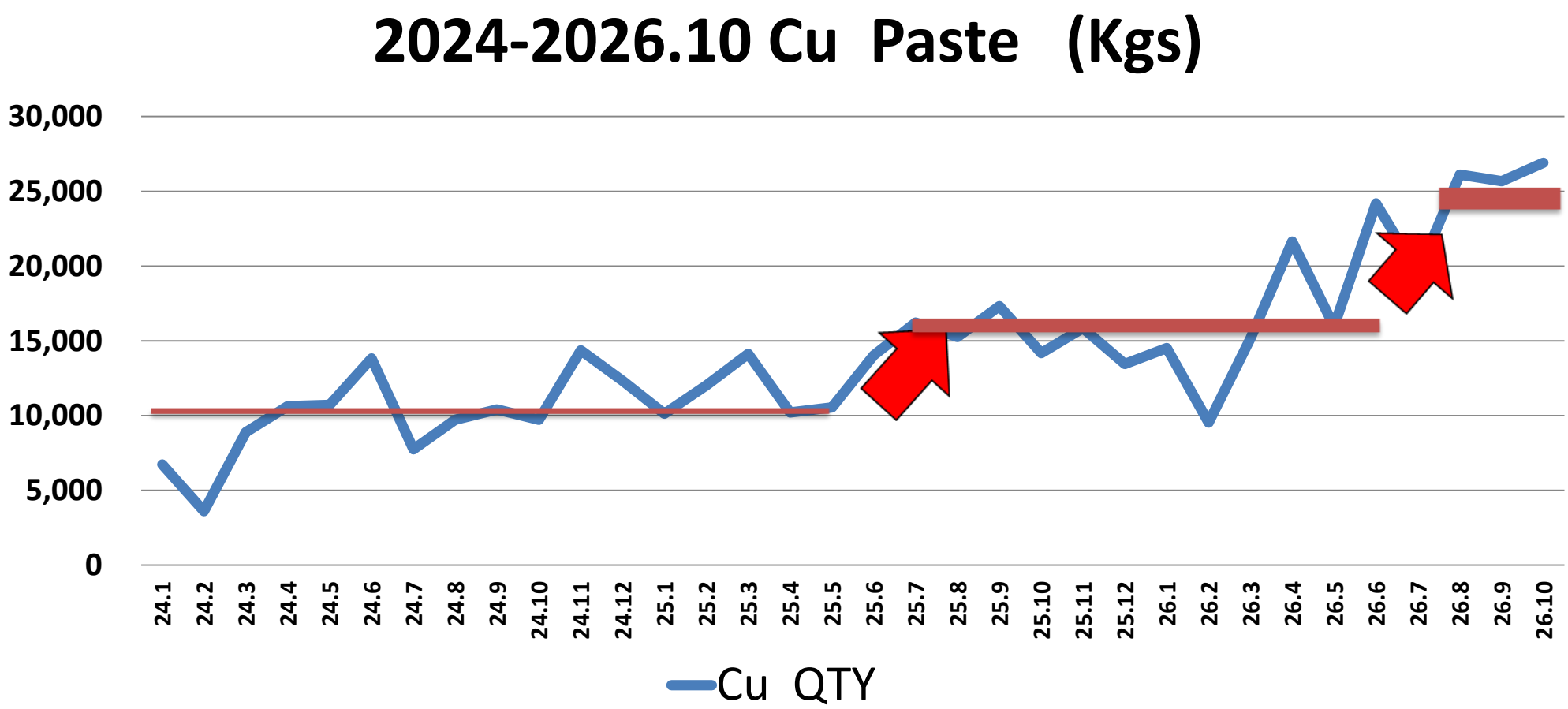
(Cash dividend:NTD$ 25.12 + Stock dividend: NTD$ 6.3675)

Applications of Conductive paste



- **Passive components: capacitors, inductors and resistors (silver and copper pastes).**
- **IC and LED packaging: die attach and curing.**
- **Robotics: sensing components and electronic skin.**
- **AI applications: advanced-packaging thermal solutions, TGV and high-speed flexible circuits.**
- **PCB via filling and solar-cell back-side silver paste.**

MLCC Copper paste shipment volume 50%



Next-generation heat dissipation: T1M1 semi-sintered adhesive

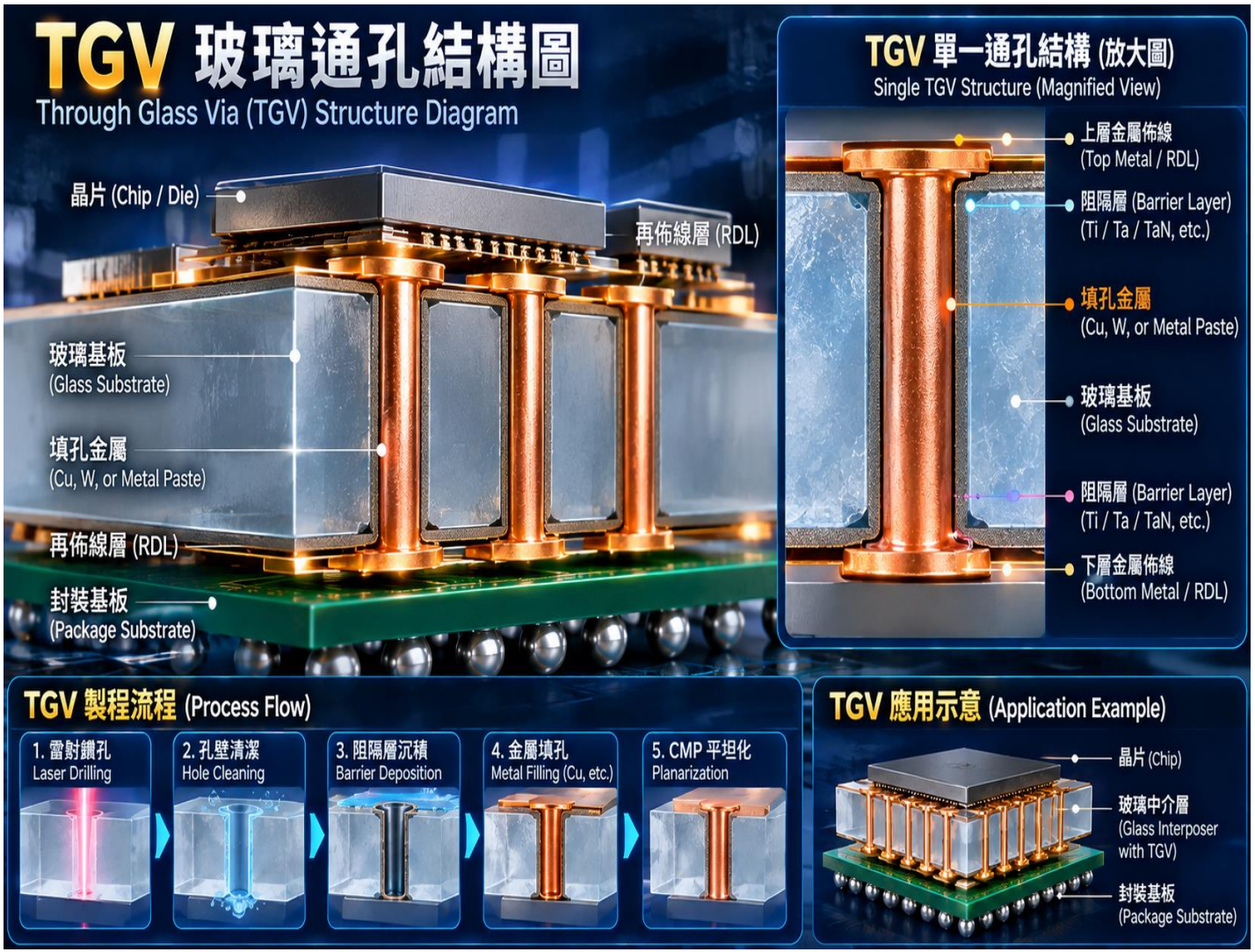
- TIM1(Thermal Interface Material)is applied in advanced



	Thermal Conductivity	Issues of the materials
Silicone	8 W/m.K	Low modulus but poor thermal conductivity
Graphite	20 W/m.K	Increase adhesive bonding
Indium	80 W/m.K	High thermal conductivity but large modulus
Semi-sintered adhesive	>80 W/m.K	High thermal conductivity Low modulus Non-porous

COPOS Advanced Packaging TGV

TGV (Through Glass Via) TGV technology enables conductive interconnections in glass substrates



- **TGV creates conductive paths through a glass substrate.**
- **Typical flow: laser drilling, cleaning, barrier deposition, metal filling and planarization.**
- **Potential applications include glass interposers and advanced heterogeneous packaging.**

TGV Technology Revolution: Electroplating >> Conductive Paste



anue 鉅亨

美股 > 國際政經

美股 玻璃基板技術大突破！半天工序縮至幾分鐘 拚明年量產

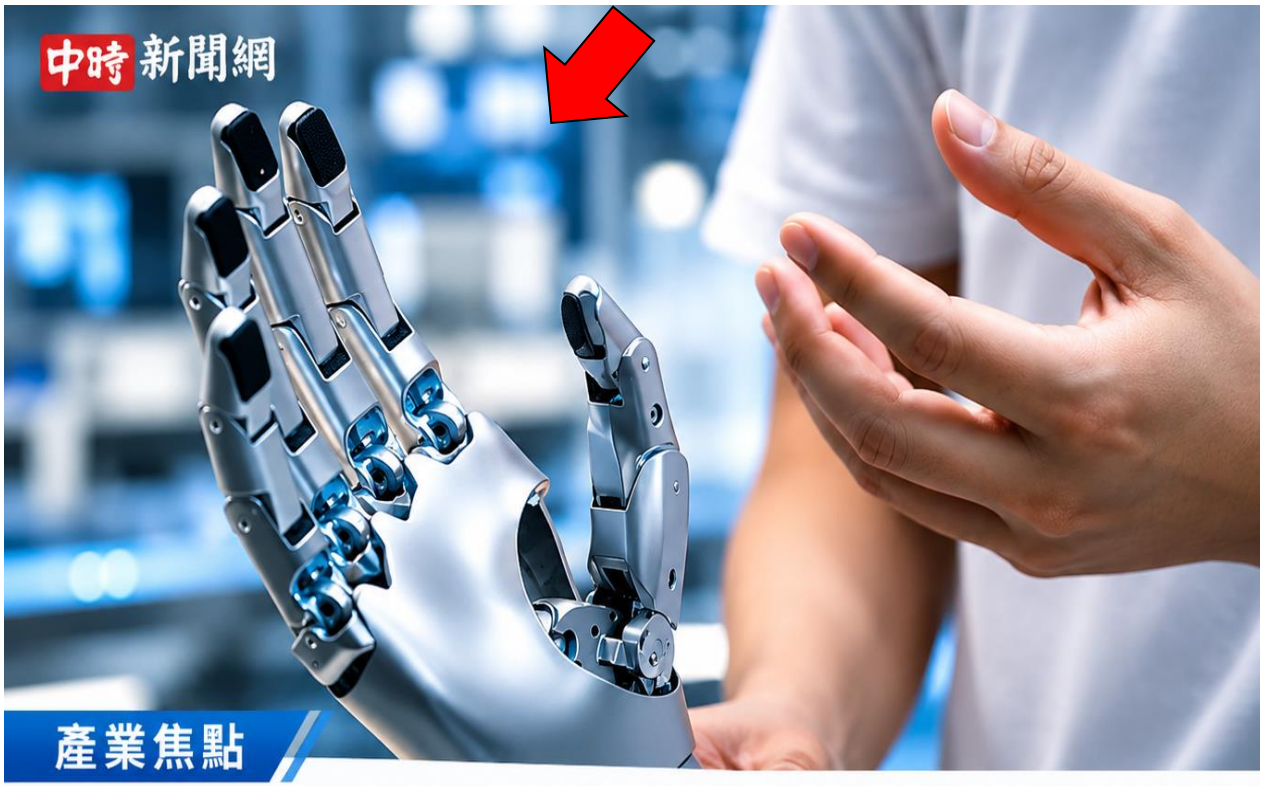
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AI新聞摘要

1. JNTC 玻璃基板 TGV 銅填充工序縮短至分鐘級，並解決空洞與銅面凹陷。
2. 美國主要半導體客戶驗證通過，業界推測為博通；台灣客戶也在測試。
3. JNTC 掌握玻璃芯完整製程，華城試產線月產能約1萬至1.2萬片，明年量產。

- Conductive paste filling is emerging as an alternative to conventional metallization approaches.
- The source references a report about shorter TGV copper-filling process times.
- Third-party article shown for industry context; not a statement of Ample customer qualification.

Application @Robot



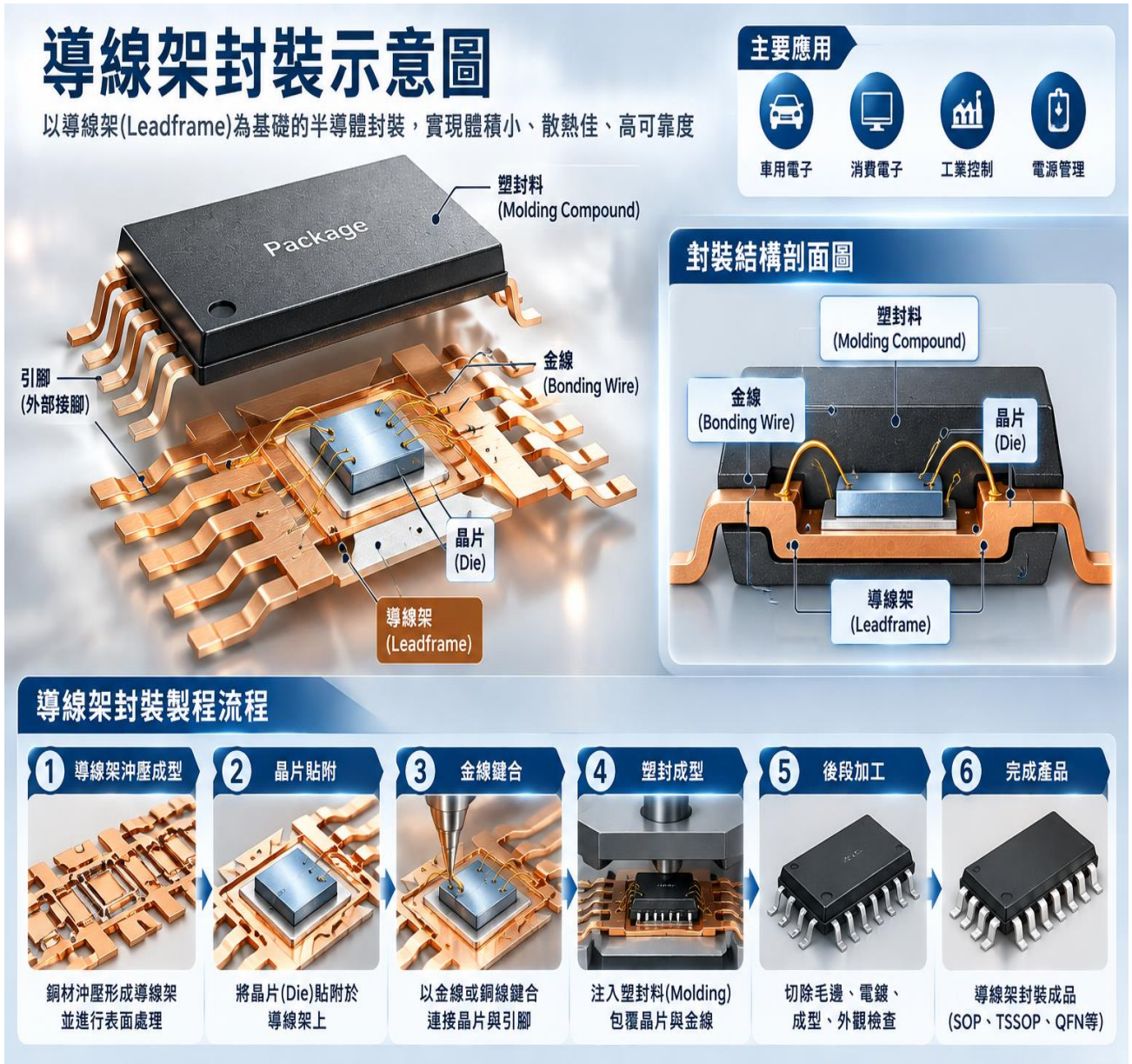
- Emerging electronic-skin applications in humanoid robotics.
- Conductive materials may support sensing elements and flexible electronic interfaces.

Application@PTFE



- Conductive via-fill for PTFE substrates used in high-frequency/high-speed electronics.
- Key requirements: reliable electrical interconnection, low transmission loss and thermal stability.
- Process illustration: drilling, hole preparation, paste filling, printing, curing and inspection.

Application for Semi-conductor&LED Packaging



- Leadframe-based packages are used in power, industrial and consumer applications.
- Typical process: leadframe preparation, die attach, wire bonding, molding, finishing and inspection.
- Conductive die-attach materials support thermal and electrical performance.

Conductive Paste: The Lifeblood of Passive Components



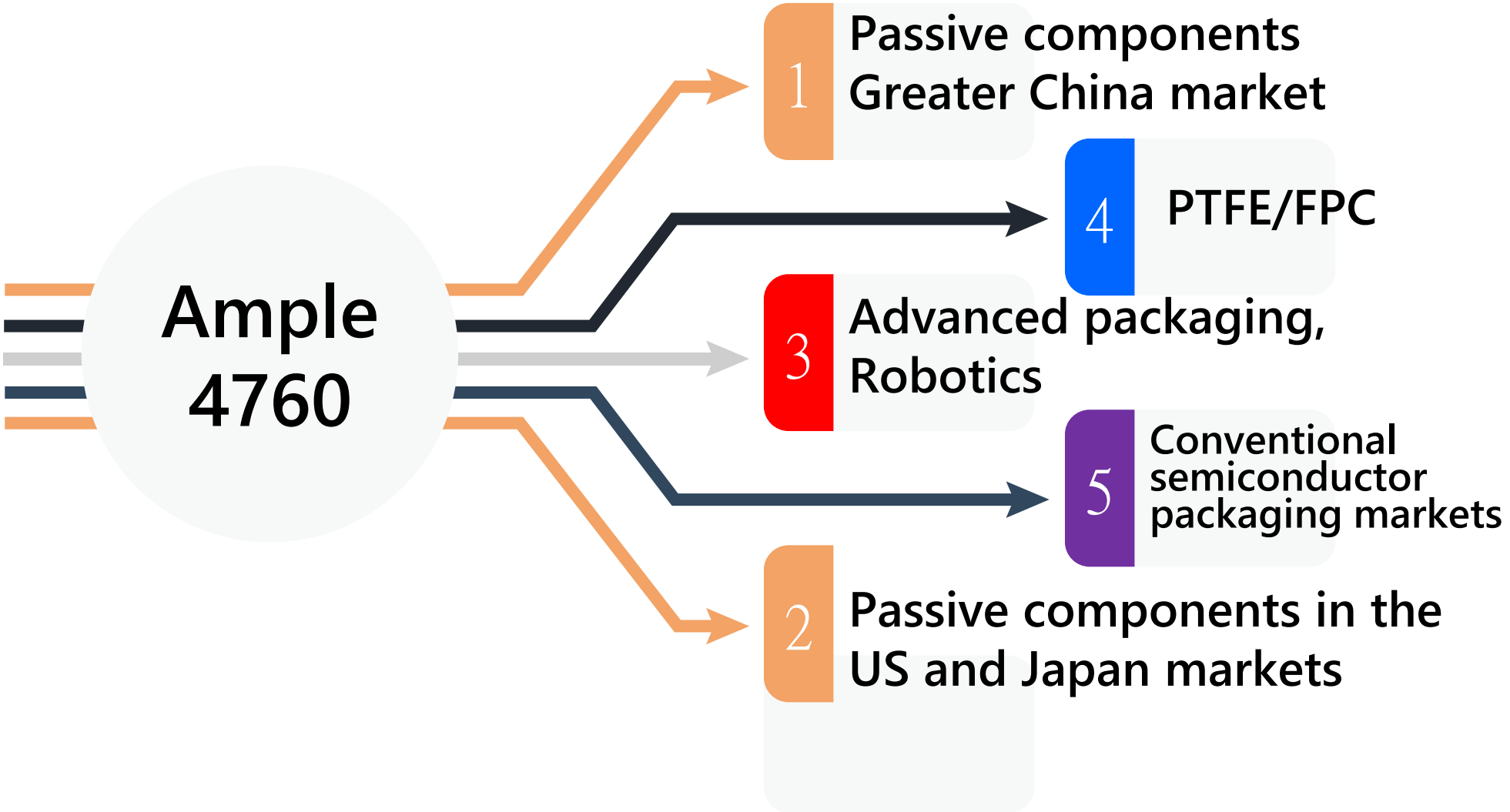
- MLCCs: internal electrodes and external termination systems.
- Chip inductors: silver conductors and terminations.
- Chip resistors: electrode and resistive structures.
- Conductive paste directly influences reliability, electrical performance and manufacturing yield.

Growth Drivers for 2027–2028



- 1. Die-attach materials
- 2. FPC / M10 PTFE conductive materials
- 3. Robotics and sensing applications
- 4. MLCC copper paste
- 5. MLCC silver paste
- 6. CoWoS advanced packaging
- 7. TGV glass via filling
- 8. Advanced PCB materials

Multiple Growth Engines



Thanks for Listening

Q & A

Line :